

1-2199298-4 ✓ ACTIVE

DIPLOMATE

TE Internal #: 1-2199298-4

Stamped & Formed, 16 Position, Low Profile, Through Hole, Tin,
-40 – 105 °C [-40 – 221 °F], DIP Sockets

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Connectors > Socket Connectors > IC Sockets > DIP Sockets > DIP Socket: Low Profile, Stamped & Formed, Open, Tin



Contact Fabrication: **Stamped & Formed**

Number of Positions: **16**

Connector Profile: **Low**

Row-to-Row Spacing: **7.62 mm [.3 in]**

Leg Style: **Through Hole**

[All DIP Socket: Low Profile, Stamped & Formed, Open, Tin \(6\)](#)

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
| Leg Style | Through Hole |

Configuration Features

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|-----------------------|----------|
| Number of Rows | 2 |
| PCB Mount Orientation | Vertical |
| Number of Positions | 16 |

Electrical Characteristics

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|-----------------------|---------|
| Insulation Resistance | 1000 MΩ |
| Contact Resistance | 20 mΩ |

Body Features

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|-------------------------|--------------|
| Sleeve Material | Brass/Copper |
| Sleeve Plating Material | Tin/Lead |
| Frame Style | Ladder |
| Connector Profile | Low |

Contact Features

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|---------------------|-----------|
| Mating Contact Type | Dual Leaf |
|---------------------|-----------|



| | |
|---|----------------------------|
| IC Socket Type | DIP |
| Contact Type | Pin |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Phosphor Bronze |
| Contact Fabrication | Stamped & Formed |
| Contact Mating Area Plating Material | Tin |
| | 60 µin |
| Contact Current Rating (Max) | 1 A |
| Termination Features | |
| | 3 in |
| Termination Method to PCB | Through Hole - Solder |
| Mechanical Attachment | |
| Mating Alignment Type | Polarization |
| Mating Alignment | With |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Housing Material | PBT GF30 |
| Housing Color | Black |
| Centerline (Pitch) | 2.54 mm[.1 in] |
| Dimensions | |
| Profile Height from PCB | 5.1 mm[.2 in] |
| Product Length | 20.32 mm[.8 in] |
| Row-to-Row Spacing | 7.62 mm[.3 in] |
| Usage Conditions | |
| Operating Temperature Range | -40 – 105 °C[-40 – 221 °F] |
| Operation/Application | |
| Circuit Application | Signal |
| Industry Standards | |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Tubes per Box | 2 |
| Packaging Quantity | 30 |



| | |
|------------------|------------------|
| Packaging Method | Box & Tube, Tube |
|------------------|------------------|

Other

| | |
|-------------------|------|
| Quantity per Tube | 3000 |
|-------------------|------|

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC |
| Halogen Content | Not Low Halogen - contains Br or Cl > 900 ppm. |
| Solder Process Capability | Wave solder capable to 240°C |

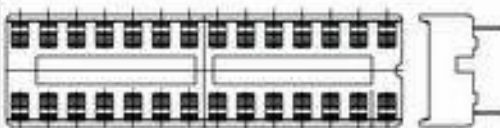
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

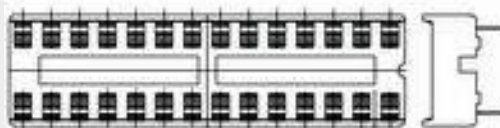
Customers Also Bought



TE Part #1-2199298-6
DIP Socket: Low Profile, Stamped & Formed, Open, Tin



TE Part #1-2199298-8
24P,DIP SKT,300 CL,LDR,PB FREE



TE Part #1-2199298-1
6P,DIP SKT,300 CL,LDR,PB FREE



TE Part #1969814-1
06P UMNL PIN HDR ASSY, PIN V0 GW



Documents

Product Drawings

16P,DIP SKT,300 CL,LDR,PB FREE

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_1-2199298-4_A.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1-2199298-4_A.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1-2199298-4_A.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[DIP Sockets Quick Reference Guide \(EN\)](#)

English